

Title (en)

MULTI-LAYER CERAMIC SUBSTRATE, AND METHOD AND DEVICE FOR PRODUCING THE SAME

Title (de)

MEHRSCHICHTIGES KERAMISCHES SUBSTRAT UND VERFAHREN UND EINRICHTUNG ZU SEINER HERSTELLUNG

Title (fr)

SUBSTRAT CERAMIQUE MULTICOUCHES, PROCEDE ET DISPOSITIF DE PRODUCTION DUDIT SUBSTRAT

Publication

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Application

**EP 03734905 A 20030131**

Priority

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Abstract (en)

[origin: US2004089472A1] This invention provides a multilayer ceramic substrate which has a consistent quality, and which has with no swelling or collapse in the inner periphery of the cavity, wherein the bottom of the cavity is flat to enable stable packaging of the desired device at a high precision, and wherein L and C can be formed by the internal conductor at a high precision; and a method for producing a multilayer ceramic substrate and an apparatus therefor by which a multilayer ceramic substrate can be readily produced in a simple procedure by using an apparatus of simple structure. This invention has realized a multilayer ceramic substrate comprising a laminate constituted from laminated ceramic layers 1a to 1h and internal conductors 3 formed between the ceramic layers 1a to 1h, wherein the laminate has end surfaces on opposite ends of its thickness direction, and the laminate is formed with a cavity 2 which opens to at least one end surface of the laminate, and wherein the multilayer ceramic substrate is provided at least with a capacitor and/or an inductor constituted by the internal conductors 3; its production method; and an apparatus used in such production.

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IPC 8 full level

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